

WHAT IS CLAIMED IS:

1. A housing for enclosing an electronic element of an electronic device,
comprising:
 - a first hole for injecting a substance thereinto;
 - 5 a second hole for evacuating air; and
 - two stop members inserted in the holes for sealing after the injection so that
the electronic element is adapted to be waterproof and vibration-proof, and has
a predetermined heat dissipation capability.
- 10 2. The housing of claim 1, wherein the housing is formed of plastic material
without electromagnetic waves shielding capability.
3. The housing of claim 2, wherein the plastic material is rubber.
4. The housing of claim 1, wherein the substance is fluid of nonconductive,
non-corrosive, and high heat transfer capability.
5. The housing of claim 4, wherein the fluid is silicon oil.
- 15 6. The housing of claim 4, wherein the fluid is hydro oil.
7. The housing of claim 1, wherein the substance is semisolid.